

*IGBT* 

# SGH25N120RUF

## Short Circuit Rated IGBT

## **General Description**

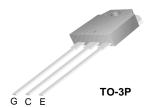
Fairchild's RUF series of Insulated Gate Bipolar Transistors (IGBTs) provides low conduction and switching losses as well as short circuit ruggedness. The RUF series is designed for applications such as motor control, uninterrupted power supplies (UPS) and general inverters where short circuit ruggedness is a required feature.

### **Features**

- Short circuit rated 10 $\mu$ s @ T<sub>C</sub> = 100°C, V<sub>GE</sub> = 15V
- High speed switching
- Low saturation voltage :  $V_{CE(sat)} = 2.3 \text{ V} @ I_{C} = 25 \text{A}$
- High input impedance

## **Applications**

AC & DC motor controls, general purpose inverters, robotics, and servo controls.





## Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Description		SGH25N120RUF	Units
V <sub>CES</sub>	Collector-Emitter Voltage		1200	V
V <sub>GES</sub>	Gate-Emitter Voltage		± 25	V
	Collector Current	@ $T_C = 25^{\circ}C$	40	А
I <sub>C</sub>	Collector Current	@ T <sub>C</sub> = 100°C	25	А
I <sub>CM (1)</sub>	Pulsed Collector Current	-	75	А
	Short Circuit Withstand Time	@ T <sub>C</sub> = 100°C	10	μs
T <sub>SC</sub>	Maximum Power Dissipation	@ $T_C = 25^{\circ}C$	270	W
	Maximum Power Dissipation	@ T <sub>C</sub> = 100°C	108	W
TJ	Operating Junction Temperature		-55 to +150	°C
T <sub>stg</sub>	Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C

#### Notes

(1) Repetitive rating : Pulse width limited by max. junction temperature

## **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.46	°C/W
$R_{\theta JA}$	Thermal Desistance Junction to Ambient		40	°C/W

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Cha	racteristics					
BV <sub>CES</sub>	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 1mA$	1200			V
$\Delta B_{VCES}/$ $\Delta T_J$	Temperature Coefficient of Breakdown Voltage	V <sub>GE</sub> = 0V, I <sub>C</sub> = 1mA		0.6		V/°C
I <sub>CES</sub>	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			1	mA
I <sub>GES</sub>	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 100	nA
On Char	racteristics					
V <sub>GE(th)</sub>	G-E Threshold Voltage	$I_C = 25$ mA, $V_{CE} = V_{GE}$	3.5	5.5	7.5	V
	Collector to Emitter	$I_C = 25A$ , $V_{GE} = 15V$		2.3	2.7	V
$V_{CE(sat)}$	Saturation Voltage	$I_C = 40A$ , $V_{GE} = 15V$		2.8		V
Dvnami	c Characteristics	, 5	1	1		1.
C <sub>ies</sub>	Input Capacitance	V <sub>CE</sub> = 30V, V <sub>GE</sub> = 0V,		2400		pF
C <sub>oes</sub>	Output Capacitance	f = 1MHz		220		pF
C <sub>res</sub>	Reverse Transfer Capacitance			70		pF
t <sub>d(on)</sub>	ng Characteristics Turn-On Delay Time			30		ns
	•					
t <sub>r</sub>	Rise Time	.,		60		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 600 \text{ V}, I_{C} = 25\text{A},$		70	130	ns
t <sub>f</sub>	Fall Time	$R_G = 10\Omega$ , $V_{GE} = 15V$ ,		150	200	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 25°C		1.60		mJ
E <sub>off</sub>	Turn-Off Switching Loss			1.63		mJ
E <sub>ts</sub>	Total Switching Loss			3.23	4.55	mJ
t <sub>d(on)</sub>	Turn-On Delay Time			30		ns
t <sub>r</sub>	Rise Time	$V_{CC} = 600 \text{ V}, I_{C} = 25\text{A},$		70		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$R_{G} = 10\Omega, V_{GE} = 15V,$		90	165	ns
t <sub>f</sub>	Fall Time	Inductive Load, $T_C = 125^{\circ}C$		200	270	ns
E <sub>on</sub>	Turn-On Switching Loss			1.88		mJ
E <sub>off</sub>	Turn-Off Switching Loss			2.50		mJ
E <sub>ts</sub>	Total Switching Loss			4.35	6.31	mJ
T <sub>sc</sub>	Short Circuit Withstand Time	$V_{CC} = 600 \text{ V}, V_{GE} = 15 \text{V}$ @ $T_{C} = 100 ^{\circ}\text{C}$	10			μs
$Q_g$	Total Gate Charge	V600 V I = 25^		110	165	nC
Q <sub>ge</sub>	Gate-Emitter Charge	$V_{CE} = 600 \text{ V}, I_{C} = 25\text{A},$		18	27	nC
Q <sub>gc</sub>	Gate-Collector Charge	V <sub>GE</sub> = 15V		55	83	nC
L <sub>e</sub>	Internal Emitter Inductance	Measured 5mm from PKG		14		nH

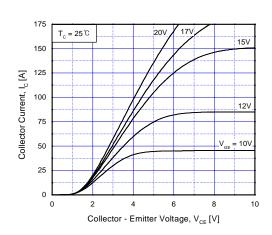
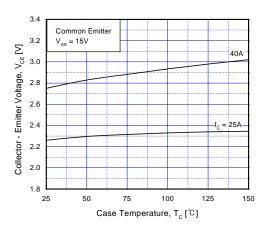


Fig 1. Typical Output Characteristics

Fig 2. Typical Saturation Voltage Characteristics



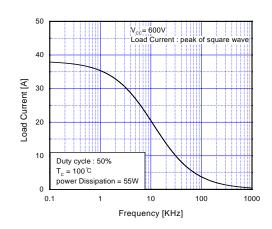
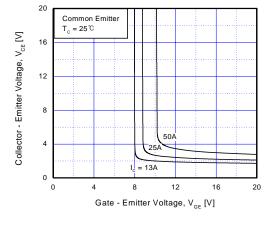


Fig 3. Saturation Voltage vs. Case Temperature at Variant Current Level

Fig 4. Load Current vs. Frequency



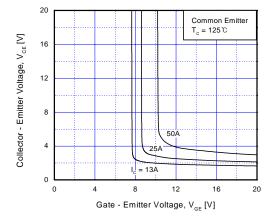
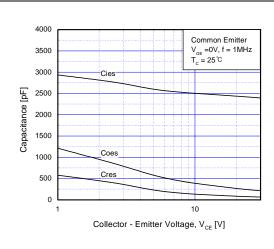


Fig 5. Saturation Voltage vs. V<sub>GE</sub>

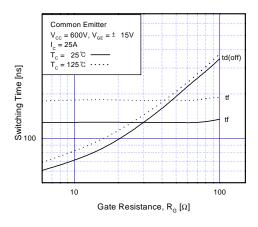
Fig 6. Saturation Voltage vs.  $V_{\rm GE}$ 



Common Emitter  $V_{cc} = 600V, V_{cg} = \pm 15V$   $I_c = 25\%$   $I_c = 25\%$   $I_c = 125\%$  ....  $I_c = 125\%$  ....  $I_c = 120\%$  ....  $I_c = 120\%$ 

Fig 7. Capacitance Characteristics

Fig 8. Turn-On Characteristics vs.
Gate Resistance



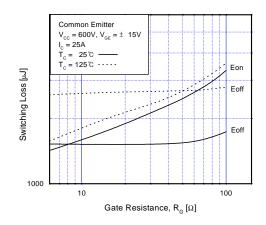
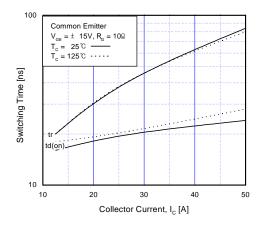


Fig 9. Turn-Off Characteristics vs.
Gate Resistance

Fig 10. Switching Loss vs. Gate Resistance



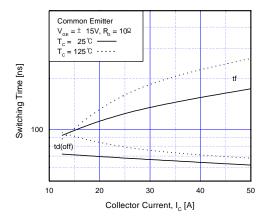
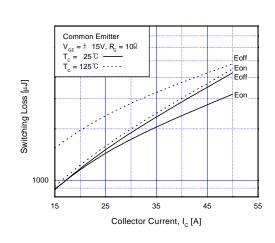


Fig 11. Turn-On Characteristics vs. Collector Current

Fig 12. Turn-Off Characteristics vs.
Collector Current



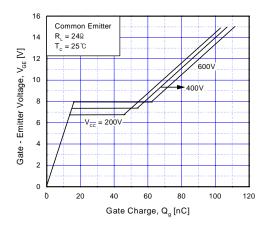
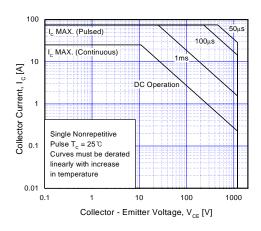


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics



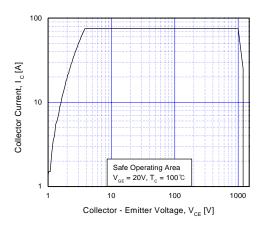


Fig 15. SOA Characteristics

Fig 16. Turn-Off SOA

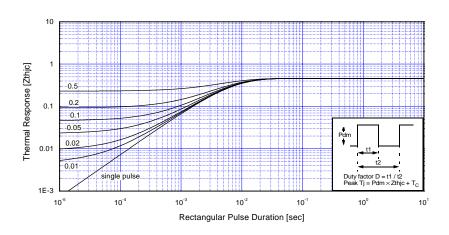
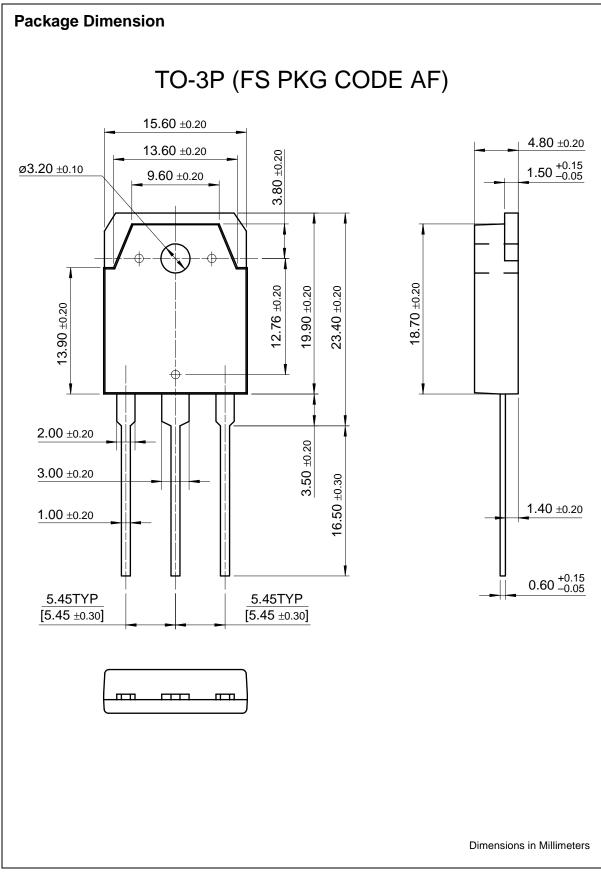


Fig 17. Transient Thermal Impedance of IGBT



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